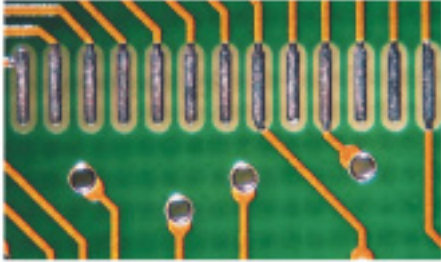


### 用于基板处理（锡棒、锡丝） SN100CL

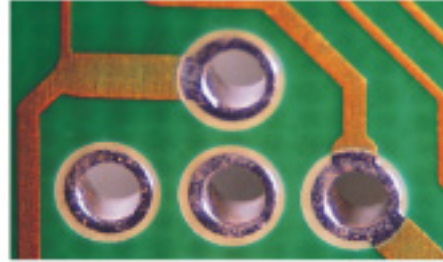
焊锡流动性与锡—铅共晶焊锡相同，间距细微，及细小孔洞也可均匀整平。

#### Hot Air Solder Leveling (HASL) SN100CL

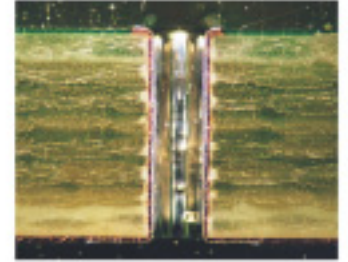
SN100CL provides a smooth bright finish and clear through holes at coating temperatures of 265°C. The SN100CL HASL process can provide the electronics industry with lead-free boards with a solderable shelf life of over a year.



无锡桥  
Bridge-free coating on 0.8mm pitch pads



焊盘、孔内均一、外表光滑  
Smooth uniform coating on pads and hole walls



焊盘、孔内及上部镀锡均匀。  
Uniform coating on pads and hole walls, even on the shoulder

### 用于电镀阳极（锡球、锡片、锡板） SN100CP

电解性强、残渣发生量少，最适用于元件引脚的电镀，还可抑制发生锡须。

#### Anode for Electroplating (Button, Tip, Plate) SN100CP

SN100CP, available as ball, button, bar and plate anodes provides excellent performance in panel or reel-to-reel Sn-Cu plating systems providing high anode efficiency and generating very little sludge.



使用电镀SN100CP 黄铜插头  
Brass connector pins electroplated with SN100CP

### 用于引脚末端处理的高温焊锡（锡棒、锡丝） SN100C3 SN100C4

用于引脚末端处理的高温焊锡，能把铜腐蚀控制在最小限度。

#### For High Temperature Dip Soldering and Tinning SN100C3 • SN100C4

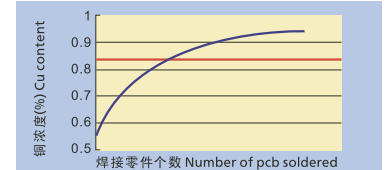
When high solder temperatures to burn insulating enamels off copper wire erosion of the copper wire can be a problem. The higher copper contents of SN100C3 and SN100C4 make it possible to carry out dip soldering with minimum copper erosion at temperature up to 400°C.

焊锡合金 温度400°C ±4°C alloy code at 400°C ±4°C	铜线的平均破断时间（秒） the average of failure of copper wire (sec)	
	直径0.29mm 0.29mm diameter	直径0.44mm 0.44mm diameter
SN100C	32	76
SN100C3	94	160
SN100C4	119	234
Sn-Cu二元合金	31	62
SN97C	24	55
SN96CI	41	85
H63A	67	143

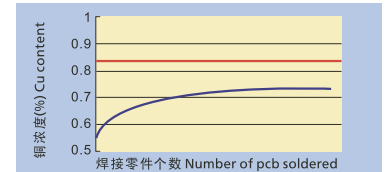
### 锡槽的铜成分管理方法 Managing the Copper of the SN100C Wave Soldering Bath

在无铅制成中必须对锡槽中的铜成分进行管理。持续使用SN100C时焊锡槽中的铜成分逐渐增加。为了控制锡槽中铜浓度，追加使用SN100Ce，以降低铜浓度，铜浓度的增加会导致焊接不稳定、锡桥、空穴等不良现象。SN100Ce追加使用，使焊锡的铜成分能够长期稳定在0.6~0.85%范围内。

As the SN100C solder bath is used copper is dissolved from boards and component leads. If the copper content of the SN100C in the solder bath exceeds 0.85% there is likely to be an increase in the incidence of bridges, icicles and other defects. Nihon Superior have devised a simple but effective method of keeping the copper content in the optimum range of 0.6-0.85%. To replace solder carried off on the soldered boards a top-up alloy with a lower copper content, SN100Ce is used. For replacing solder removed during the skimming of dross the standard SN100C alloy can be used. Nihon Superior provide solder bath analyses to ensure that the copper content is in the recommended range.e.



持续使用SN100C时  
Cu content, when SN100C is used for top-up



持续使用SN100Ce时  
Cu content, when SN100Ce is used for top-up

### SN100C一览表

### SN100C Series

编号 Product code	用途 Application	融点 Melting point (°C)
SN100C	用于波峰焊、手工焊等 For wave soldering, manual, rework & repair	227-227
SN100Ce	用于调整（降低）锡槽Cu含量 For solder bath top-up to maintain the Cu-content	227-230
SN100CL	电路板热风整平处理用 For hot air solder leveling (HASL)	227-227
SN100CP	用于电镀阳极 Anode for electroplating	-
SN100C3	用于波引脚末端处理的高温焊锡 For high temperature dip soldering and tinning	227-310
SN100C4		227-340

